PC716V0NSZX/ PC716V0YSZX

High Sensitivity and High Collector Current Type Photocoupler

■ Features

1. High collector current (I_C:MAX. 200mA)
2. High sensitivity (CTR:MIN. 1 000%)
3. Isolation voltage (Viso (rms):5kV)
4. Recognized by UL, file No.E64380
   Approved by TÜV (VDE0884)(**PC716V0YSZX**)
5. 6-pin DIP package

■ Applications

1. Home appliances
2. Programmable controllers
3. Peripheral equipment of personal computers

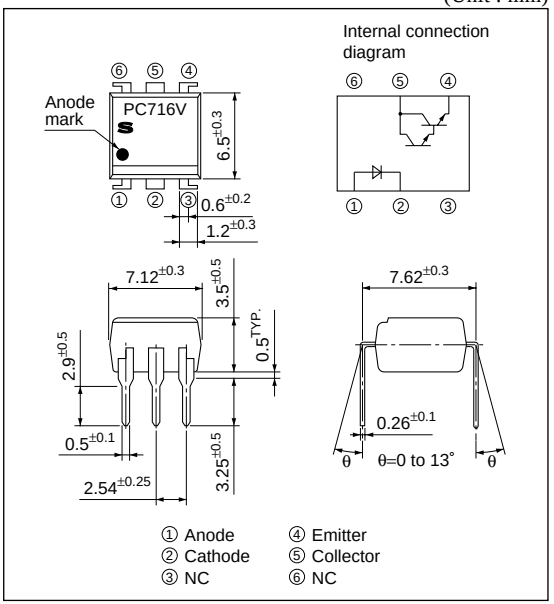
■ Model Line-up

Model No.	* Safty Standard Approval	
	UL	TÜV(VDE0884)
PC716V0NSZX	○	−
PC716V0YSZX	○	○

* Application Model No. PC716V

■ Outline Dimensions

(Unit : mm)



■ Absolute Maximum Ratings

(Ta=25°C)

Parameter		Symbol	Rating	Unit
Input	Forward current	I_F	50	mA
	*1 Peak forward current	I_{FM}	1	A
	Reverse voltage	V_R	6	V
	Power dissipation	P	70	mW
Output	Collector-emitter voltage	V_{CEO}	35	V
	Emitter-collector voltage	V_{ECO}	6	V
	Collector current	I_C	200	mA
	Collector power dissipation	P_C	300	mW
Total power dissipation		P_{tot}	350	mW
*2 Isolation voltage		$V_{iso\ (rms)}$	5	kV
Operating temperature		T_{opr}	−25 to +100	°C
Storage temperature		T_{stg}	−40 to +125	°C
*3 Soldering temperature		T_{sol}	260	°C

*1 Pulse width≤100μs, Duty ratio=0.001
*2 40 to 60%RH, AC for 1 min
*3 For 10 s

■ Electro-optical Characteristics

(Ta=25˚C)

Parameter			Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Input	Forward voltage		V_F	I_F=10mA	–	1.2	1.4	V
	Peak forward voltage		V_{FM}	I_{FM}=0.5A	–	–	3.0	V
	Reverse current		I_R	V_R=4V	–	–	10	μA
	Terminal capacitance		C_t	V=0, f=1kHz	–	30	250	pF
Output	Collector dark current		I_{CEO}	V_{CE}=10V, I_F=0	–	–	10^{-6}	A
Transfer characteristics	Collector current		I_C	I_F=1mA, V_{CE}=2V	10	60	150	mA
	Collector-emitter saturation voltage		$V_{CE(sat)}$	I_F=20mA, I_C=10mA	–	–	1.2	V
	Isolation resistance		R_{ISO}	DC500V, 40 to 60%RH	5×10^{10}	10^{11}	–	Ω
	Floating capacitance		C_f	V=0, f=1MHz	–	0.6	1.0	pF
	Cut-off frequency		f_C	V_{CE}=2V, I_C=10mA, R_L=100Ω, −3dB	–	3	–	kHz
	Response time	Rise time	t_r	V_{CE}=2V, I_C=20mA, R_L=100Ω	–	130	400	μs
		Fall time	t_f		–	60	350	μs

Fig.1 Forward Current vs. Ambient Temperature

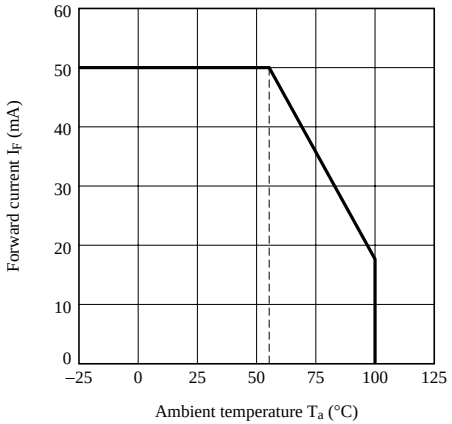


Fig.2 Collector Power Dissipation vs. Ambient Temperature

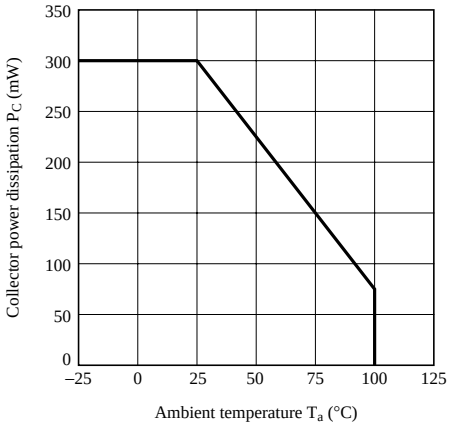


Fig.3 Peak Forward Current vs. Duty Ratio

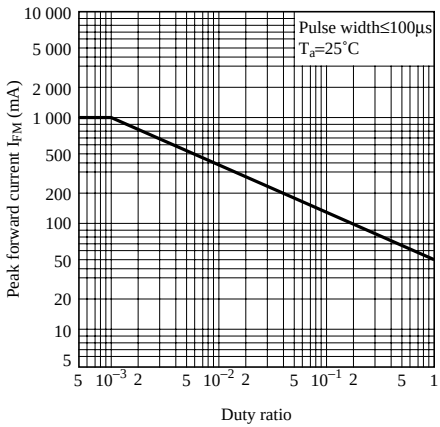


Fig.4 Forward Current vs. Forward Voltage

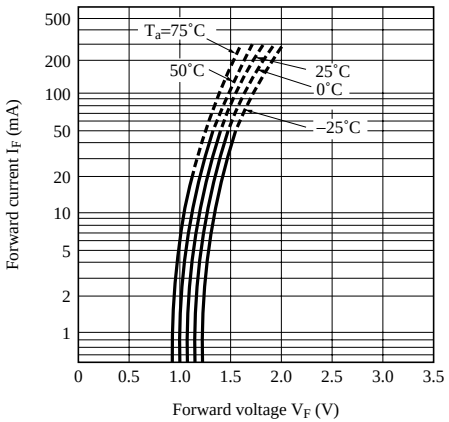


Fig.5 Current Transfer Ratio vs. Forward Current

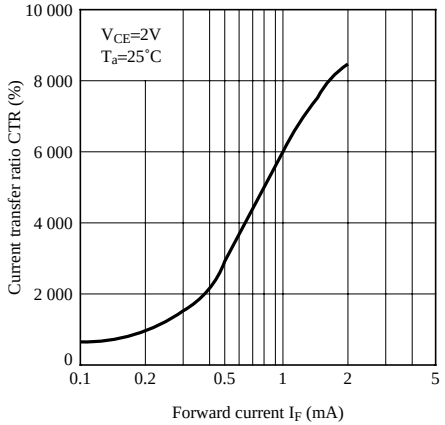


Fig.6 Collector Current vs. Collector-emitter Voltage

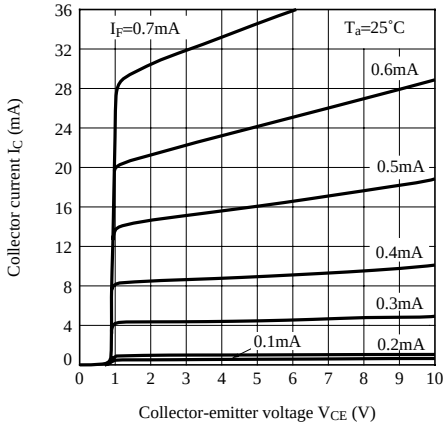


Fig.7 Collector Current vs. Collector-emitter Voltage

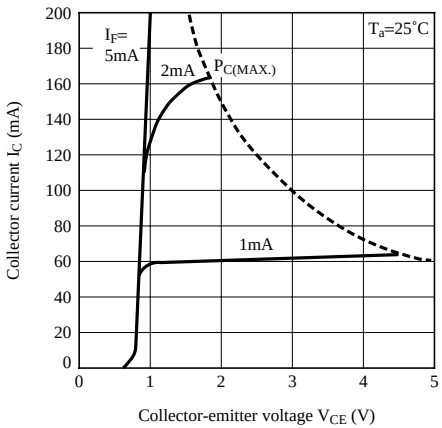


Fig.8 Relative Current Transfer Ratio vs. Ambient Temperature

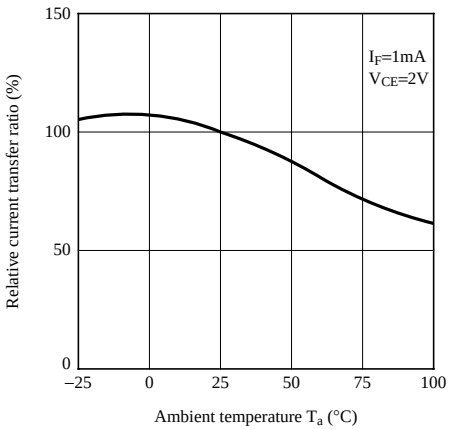


Fig.9 Collector - emitter Saturation Voltage vs. Ambient Temperature

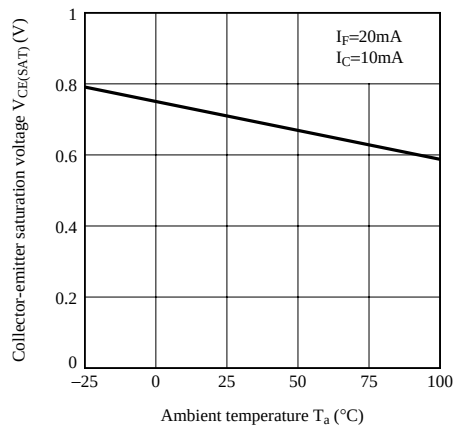


Fig.10 Collector Dark Current vs. Ambient Temperature

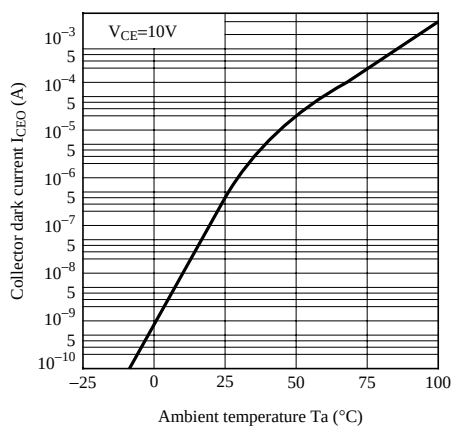


Fig.11 Response Time vs. Load Resistance

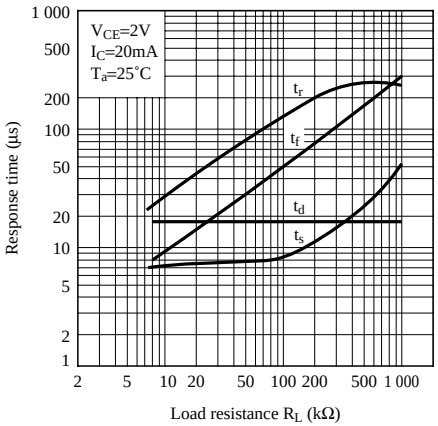


Fig.12 Test Circuit for Response Time

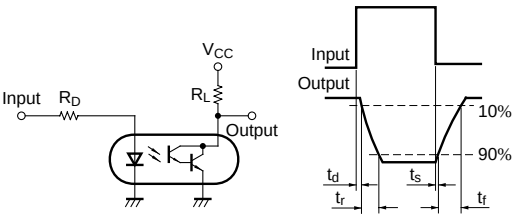


Fig.13 Frequency Response

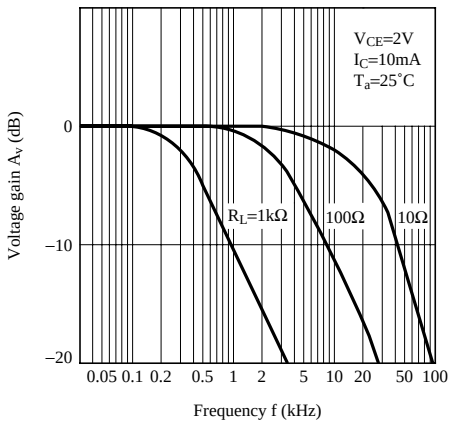
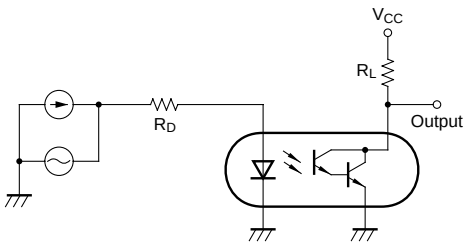


Fig.14 Test Circuit for Frequency Response



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— Industrial control
— Audio visual equipment
— Consumer electronics

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— Various safety devices, etc.

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